

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>DEEPUKUMAR M. NAIR</td> <td>01/25/2013</td> </tr> <tr> <td>MICHAEL ARNETT SMITH</td> <td>02/12/2013</td> </tr> <tr> <td>BRADLEY THRASHER</td> <td>02/04/2013</td> </tr> <tr> <td>JAMES M. PARISI</td> <td>01/25/2013</td> </tr> <tr> <td>JOAO CARLOS MALERBI</td> <td>02/07/2013</td> </tr> <tr> <td>ELIZABETH D. HUGHES</td> <td>01/28/2013</td> </tr> </tbody> </table>		Name	Execution Date	DEEPUKUMAR M. NAIR	01/25/2013	MICHAEL ARNETT SMITH	02/12/2013	BRADLEY THRASHER	02/04/2013	JAMES M. PARISI	01/25/2013	JOAO CARLOS MALERBI	02/07/2013	ELIZABETH D. HUGHES	01/28/2013
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<table border="1"> <tr> <td>Name:</td> <td>E. I. DU PONT DE NEMOURS AND COMPANY</td> </tr> <tr> <td>Street Address:</td> <td>4417 LANCASTER PIKE</td> </tr> <tr> <td>Internal Address:</td> <td>BARLEY MILL PLAZA 25</td> </tr> <tr> <td>City:</td> <td>WILMINGTON</td> </tr> <tr> <td>State/Country:</td> <td>DELAWARE</td> </tr> <tr> <td>Postal Code:</td> <td>19805</td> </tr> </table>		Name:	E. I. DU PONT DE NEMOURS AND COMPANY	Street Address:	4417 LANCASTER PIKE	Internal Address:	BARLEY MILL PLAZA 25	City:	WILMINGTON	State/Country:	DELAWARE	Postal Code:	19805		
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CORRESPONDENCE DATA															
Fax Number:	3023553982														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
Phone:	3029922425														
Email:	CANDACE.L.CALHUM@USA.DUPONT.COM														
Correspondent Name:	JOSEPH J. DIDONATO														
Address Line 1:	4417 LANCASTER PIKE														
Address Line 2:	BARLEY MILL PLAZA 25														
Address Line 4:	WILMINGTON, DELAWARE 19805														
ATTORNEY DOCKET NUMBER:	EL1089USNP														

CH \$40.00 13749221

NAME OF SUBMITTER:

CANDACE L. CALHUM

Total Attachments: 5

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ASSIGNMENT

We, the undersigned

DEEPUKUMAR M NAIR, MICHAEL ARNETT SMITH, BRADLEY THRASHER,
JAMES M PARISI, JOAO CARLOS MALERBI, ELIZABETH D HUGHES

Hereby declare that

We are the true and first inventors of an invention entitled

MICROWAVE/MILLIMETER WAVE CHIP SCALE PACKAGE WITH INTEGRATED ANTENNA ARRAY ON MULTILAYER DIELECTRIC SUBSTRATE

which is disclosed in the United States Patent Application No. 13749221 filed on January 24, 2013 and which is identified as Case Number EL1089-US-NP.

For valuable consideration, the receipt and adequacy of which is hereby acknowledged and in fulfillment of our pre-existing obligation of assignment, we hereby:

I. Sell, assign, and transfer unto E I DU PONT DE NEMOURS AND COMPANY, a corporation organized and existing under the laws of the State of Delaware in the United States of America and having its principal place of business at Wilmington, Delaware, hereinafter referred to as the assignee, (A) the sole and entire right, title, and interest in and to: (1) the aforesaid application for Letters Patent, (2) any priority rights derived from the aforesaid application for Letters Patent by virtue of the International Convention for the Protection of Industrial Property and any other treaty or understanding for intellectual property for any and all member countries of the aforesaid International Convention or other treaty or understanding, (3) any and all our inventions, whether joint or sole, disclosed in the aforesaid application for Letters Patent, (4) any and all applications for Letters Patent for any such inventions in any country whatsoever, (5) any and all patents for any such inventions in any country whatsoever; and (B) the sole right to (1) file such applications in its name or ours, (2) file such applications under the aforesaid International Convention or other treaty or understanding, (3) have said patents granted in its name or ours, and (4) enforce said patents and to sue for and recover profits and damages for any and all infringements thereof whether past or future; and

II. Agree, whenever requested, to communicate to said assignee, its successors, assigns, and legal representatives, any facts known to us respecting said rights, to testify in any legal proceeding respecting said rights, to execute all applications, papers or instruments necessary or required by said assignee, its successors, assigns and legal representatives, to carry into effect any of the provisions of this instrument, and generally to do everything possible to aid said assignee, its successors, assigns, and legal representatives to obtain and enforce proper patent protection for said inventions in any and all countries.


DEEPUKUMAR M NAIR (L.S.)
DATE: 01/25/2013


JAMES M PARISI (L.S.)
DATE: 1.25.2013

MICHAEL ARNETT SMITH (L.S.)
DATE: _____

JOAO CARLOS MALERBI (L.S.)
DATE: _____

BRADLEY THRASHER (L.S.)
DATE: _____

ELIZABETH D HUGHES (L.S.)
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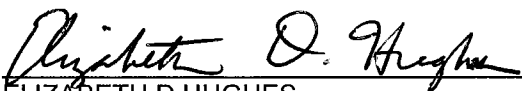
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